intersil

PA16068

Product Advisory (PA)

Subject: Correction to Standard Microcircuit Drawing 5962-15220 for Intersil Product ISL71841SEHVF (SMD PIN 5962R1522001VXC)
Publication Date: 6/24/2016
Effective Date: 6/24/2016

Revision Description:

Initial Release

Description of Change:

This advisory is to inform you that Intersil has made corrections to DLA (Defense Logistics Agency) Land and Maritime SMD (Standard Microcircuit Drawing) 5962-15220 for Intersil product ISL71841SEHVF (5962R1522001VXC). The update corrects the thermal resistance junction-to-case and junction-to-ambient for case outline X (flat pack only) as specified in paragraph 1.3 of the SMD.

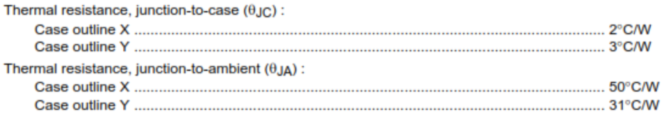
Reason for Change:

The correction aligns the SMD with the product characteristics. Details regarding the change are contained below. The updated SMD is available on the DLA website at:
http://www.landandmaritime.dla.mil/Downloads/MilSpec/Smd/15220.pdf

Changed from:

Thermal resistance, junction-to-case (θ_{JC}) .... 3°C/W
Thermal resistance, junction-to-ambient (θ_{JA}) .... 36.5°C/W

Changed to:



Thermal resistance, junction-to-case (θ_{JC}) :
  Case outline X .... 2°C/W
  Case outline Y .... 3°C/W
Thermal resistance, junction-to-ambient (θ_{JA}) :
  Case outline X .... 50°C/W
  Case outline Y .... 31°C/W

Product Identification:

Product affected by this change is identifiable via Intersil’s internal traceability system.

Qualification status: Not applicable
Sample availability: 6/24/2016
Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
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